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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Kripesh et al.
Appl. No. : 10/078,243
Filed : February 14, 2002
For : PROCESS OF FORMING METAL
SURFACES COMPATIBLE WITH
A WIRE BONDING AND
SEMICONDUCTOR
INTEGRATED CIRCUITS
MANUFACTURED BY THE
PROCESS
Examiner : L. A. Gurley
Group Art Unit : 2812

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all
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January 8, 2004

(Date)

John M. Carson, Reg. No. 34,303

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed October 8, 2003, Applicant respectfully submits
the following amendments and remarks in connection with the above-captioned application.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 5
of this paper.

Remarks/Arguments begin on page 14 of this paper.